



Material Content Data Sheet



Sales Product Name		TLE6711G		Issued		20. July 2018		
MA#		MA000971466						
Package		PG-DSO-14-1		Weight*		143.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.251	4.34	4.34	43418	43418
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		419	
	non noble metal	iron	7439-89-6	1.207	0.84		8383	
wire	non noble metal	copper	7440-50-8	49.007	34.04	34.93	340392	349299
	noble metal	gold	7440-57-5	0.340	0.24	0.24	2361	2361
	encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1148
encapsulation	plastics	epoxy resin	-	7.605	5.28		52824	
	inorganic material	silicondioxide	60676-86-0	74.895	52.02	57.41	520204	574176
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8517	8517
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7153	7153
glue	plastics	acrylic resin	-	0.478	0.33		3317	
	noble metal	silver	7440-22-4	1.693	1.18	1.51	11759	15076
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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